

Product Summary

V_{BR} MIN	I_{PP} MAX	C_{IN} TYP
6V	7.5A	0.50pF

Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability makes it ideal for use in portable applications such as USB2.0.

Applications

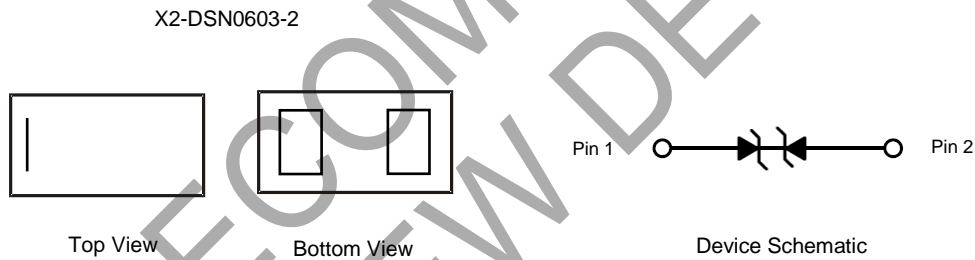
- USB2.0/USB3.0
- Computers and peripherals

Features

- Provides ESD Protection per IEC 61000-4-2 Standard: Contact $\pm 22\text{kV}$, Air $\pm 22\text{kV}$
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

Mechanical Data

- Package: X2-DSN0603-2
- Package Material: Chip Scale Package
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.0002 grams (Approximate)

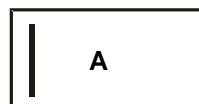


Ordering Information (Note 4)

Part Number	Package	Marking	Reel Size (inches)	Tape Width (mm)	Packing	
					Qty.	Carrier
DESD4V0X1BD2CSP-7	X2-DSN0603-2	A	7	8	10,000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



A = Product Type Marking Code
Bar Denotes Pin 1

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Condition
Peak Pulse Power Dissipation	PPP	40	W	8/20μs, per Figure 3
Peak Pulse Current	I _{PP}	7.5	A	8/20μs, per Figure 3
ESD Protection – Air Discharge	V _{ESD_AIR}	±22	kV	IEC61000-4-2 Standard
ESD Protection – Contact Discharge	V _{ESD_CONTACT}	±22	kV	IEC61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	—	—	4.0	V	—
Channel Leakage Current (Note 6)	I _{RM}	—	—	1	μA	V _{RWM} = 4V
Clamping Voltage	V _{CL}	—	5.0	—	V	I _{PP} = 7.5A, t _p = 8/20μs
		—	3.9	—		I _{PP} = 8A, TLP, t _p = 100ns
		—	5.0	—		I _{PP} = 16A, TLP, t _p = 100ns
Breakdown Voltage	V _{BR}	6	—	9	V	I _R = 1mA
Differential Resistance	R _{DYN}	—	0.2	—	Ω	TLP = 10A, t _p = 100ns
Channel Input Capacitance	C _{IN}	—	0.50	—	pF	V _R = 0V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 6. Short duration pulse test used to minimize self-heating effect.

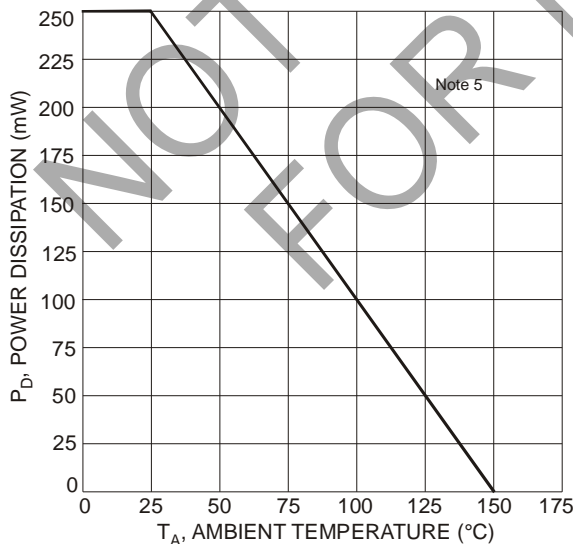


Figure 1 Power Derating Curve

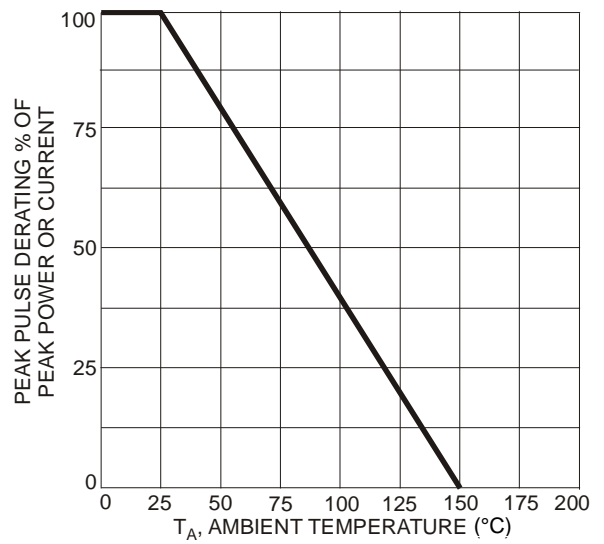
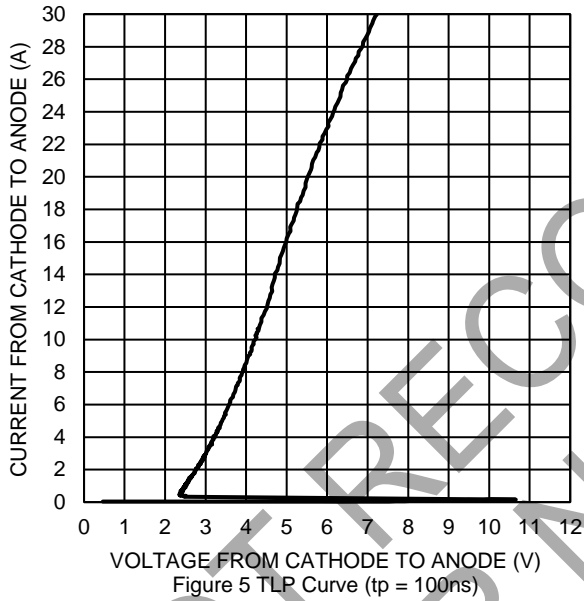
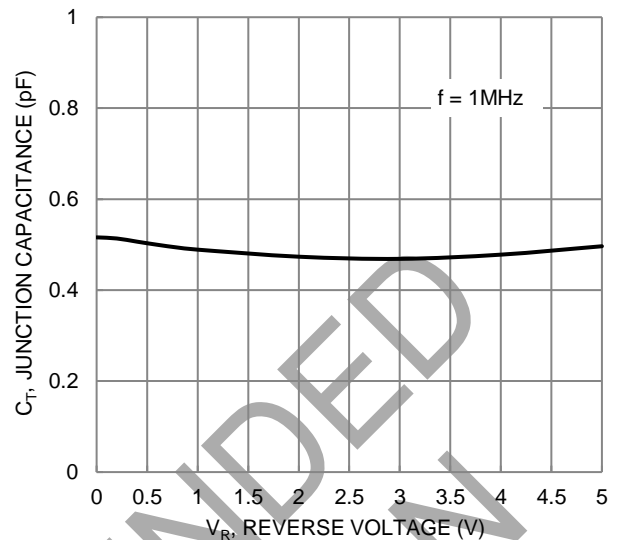
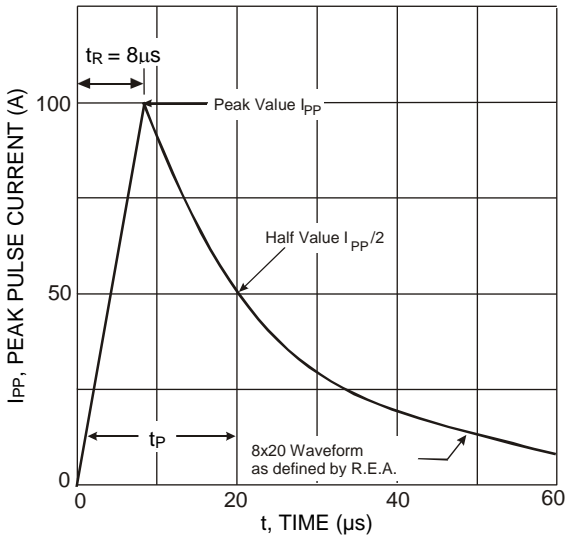


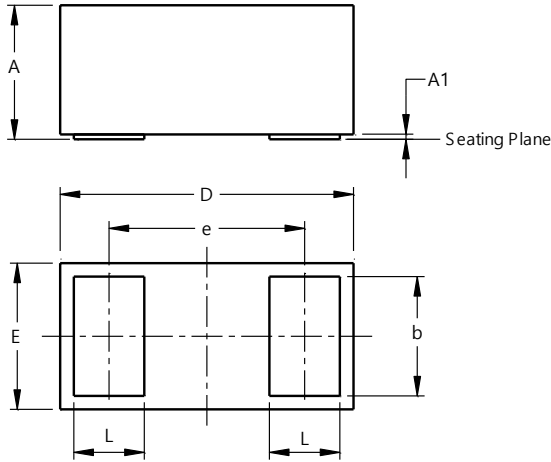
Figure 2 Pulse Derating Curve



Package Outline Dimensions (Note 7)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DSN0603-2



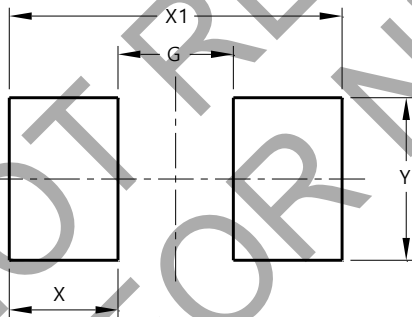
X2-DSN0603-2			
Dim	Min	Max	Typ
A	0.280	0.320	0.300
A1	0.00	0.020	0.010
b	0.220	0.260	0.240
D	0.575	0.625	0.600
E	0.275	0.325	0.300
e	-	-	0.400
L	0.120	0.160	0.140
All Dimensions in mm			

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DSN0603-2



Dimensions	Value (in mm)
G	0.206
X	0.194
Y	0.291
X1	0.594

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